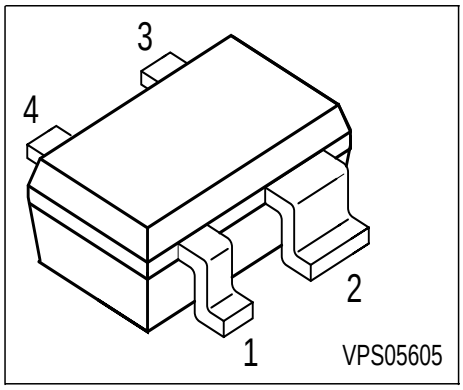
Silicon N-Channel MOSFET Tetrode

- Short-channel transistor with high S/C quality factor
- For low-noise, gain-controlled input stages up to 1 GHz



ESD: **E**lectro**s**tatic **d**ischarge sensitive device, observe handling precaution!

Type	Marking	Pin Configuration				Package
BF998W	MRs	1=D	2=S	3=G1	4=G2	SOT343

Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	12	V
Continuos drain current	I_D	30	mA
Gate 1/gate 2 peak source current	$\pm I_{G1/2SM}$	10	
Total power dissipation, T_S = 94 °C	P_{tot}	200	mW
Storage temperature	T_{stg}	55 ... 150	°C
Channel temperature	T_{ch}	150	

Thermal Resistance

Channel - soldering point[1)]	R_{thchs}	≤280	K/W

[1]For calculation of R_{thJA} please refer to Application Note Thermal Resistance

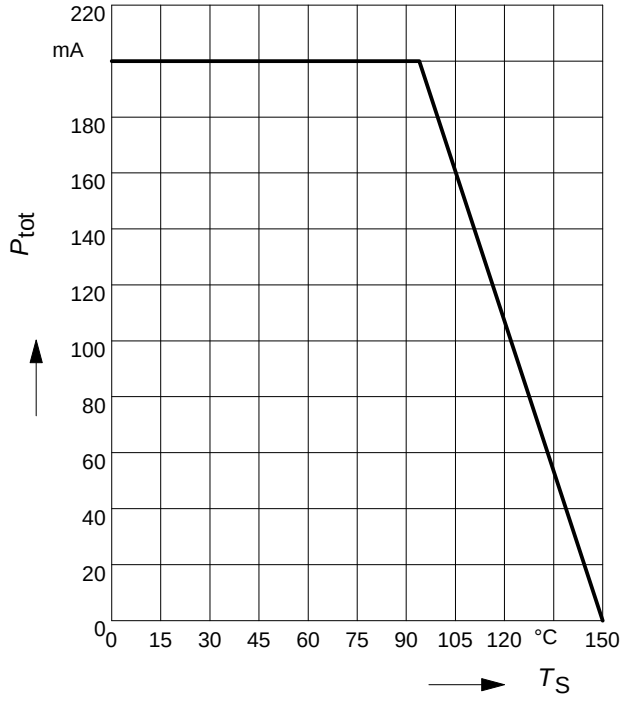
Electrical Characteristics at T_A = 25 °C; unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC characteristics					
Drain-source breakdown voltage I_D = 10 µA, V_{G1S} = -4 V, V_{G2S} = -4 V	$V_{(BR)DS}$	12	-	-	V
Gate 1 source breakdown voltage $\pm I_{G1S}$ = 10 mA, V_{G2S} = V_{DS} = 0	$\pm V_{(BR)G1SS}$	8	-	12	
Gate 2 source breakdown voltage $\pm I_{G2S}$ = 10 mA, V_{G1S} = 0 V, V_{DS} = 0 V	$\pm V_{(BR)G2SS}$	8	-	12	
Gate 1 source leakage current $\pm V_{G1S}$ = 8 V, V_{G2S} = V_{DS} = 0	$\pm I_{G1SS}$	-	-	50	nA
Gate 2 source leakage current $\pm V_{G2S}$ = 8 V, V_{G1S} = 0 V, V_{DS} = 0 V	$\pm I_{G2SS}$	-	-	50	
Drain current V_{DS} = 8 V, V_{G1S} = 0 , V_{G2S} = 4 V	I_{DSS}	2	-	18	mA
Gate 1 source pinch-off voltage V_{DS} = 8 V, V_{G2S} = 0 , I_D = 20 µA	$-V_{G1S(p)}$	-	-	2.5	V
Gate 2 source pinch-off voltage V_{DS} = 8 V, V_{G1S} = 0 , I_D = 20 µA	$-V_{G2S(p)}$	-	-	2	

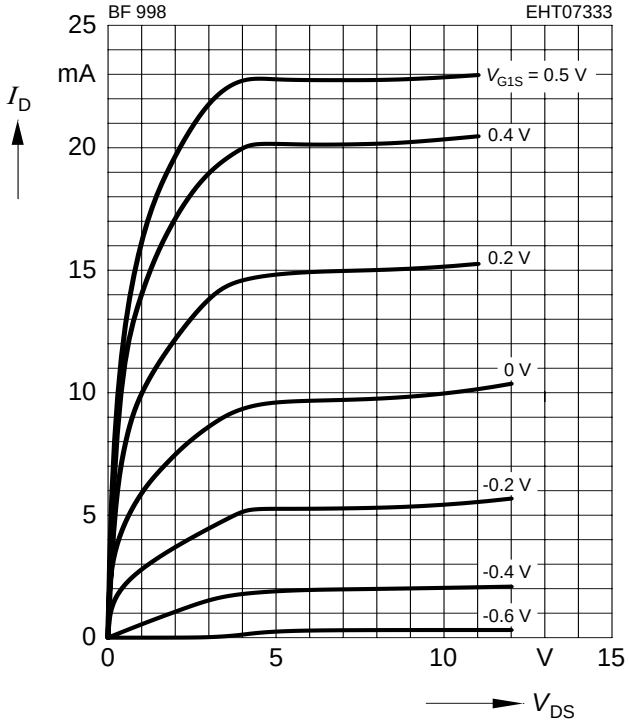
Electrical Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC characteristics					
Forward transconductance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V	g_{fs}	-	24	-	mS
Gate 1 input capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 1 MHz	C_{g1ss}	-	2.1	2.5	pF
Gate 2 input capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 1 MHz	C_{g2ss}	-	1.2	-	
Feedback capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 1 MHz	C_{dg1}	-	25	-	fF
Output capacitance V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 1 MHz	C_{dss}	-	1.1	-	pF
Power gain V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 200 MHz	G_{ps}	-	28	-	dB
Power gain V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 800 MHz	G_{ps}	-	20	-	
Noise figure V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 200 MHz	F	-	0.6	-	
Noise figure V_{DS} = 8 V, I_D = 10 mA, V_{G2S} = 4 V, f = 800 MHz	F	-	1	-	
Gain control range V_{DS} = 8 V, VG2S = 4 ... -2V, f = 800 MHz	ΔG_{ps}	40	-	-	

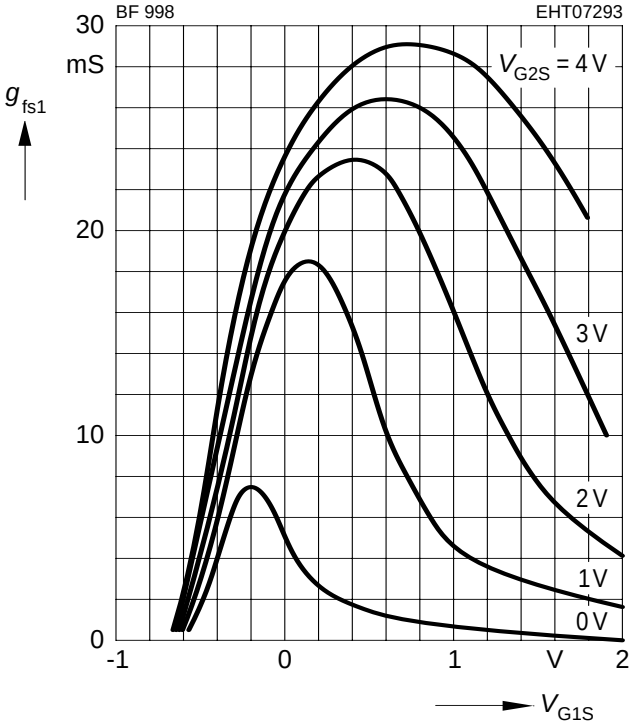
Total power dissipation $P_{tot} = f(T_S)$



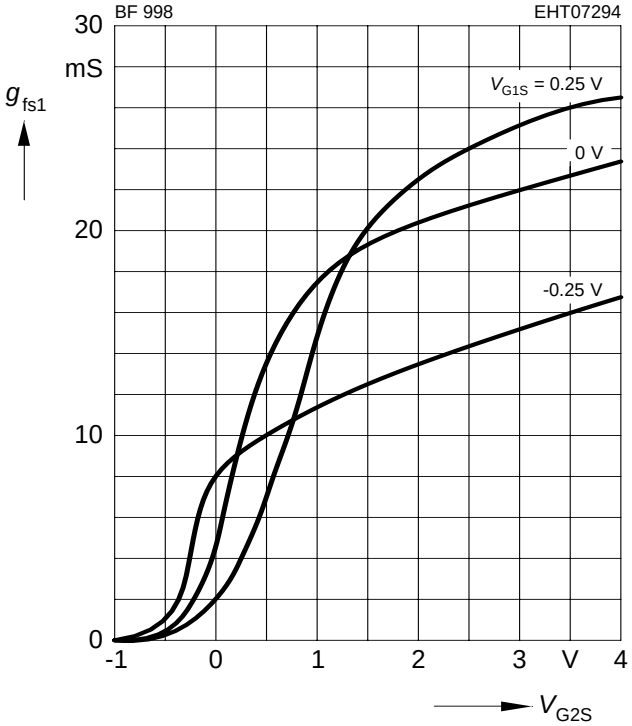
Output characteristics $I_D = f(V_{DS})$



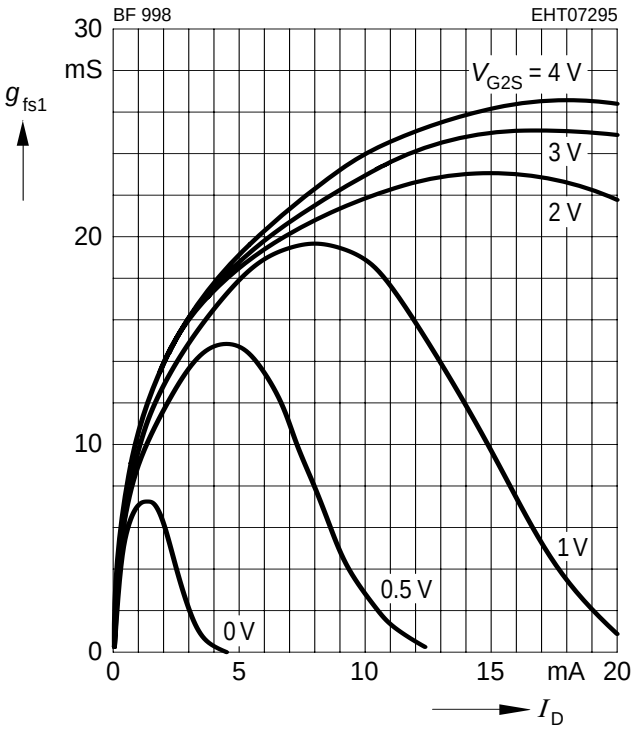
Gate 1 forward transconductance
$g_{fs1} = f(V_{G1S})$



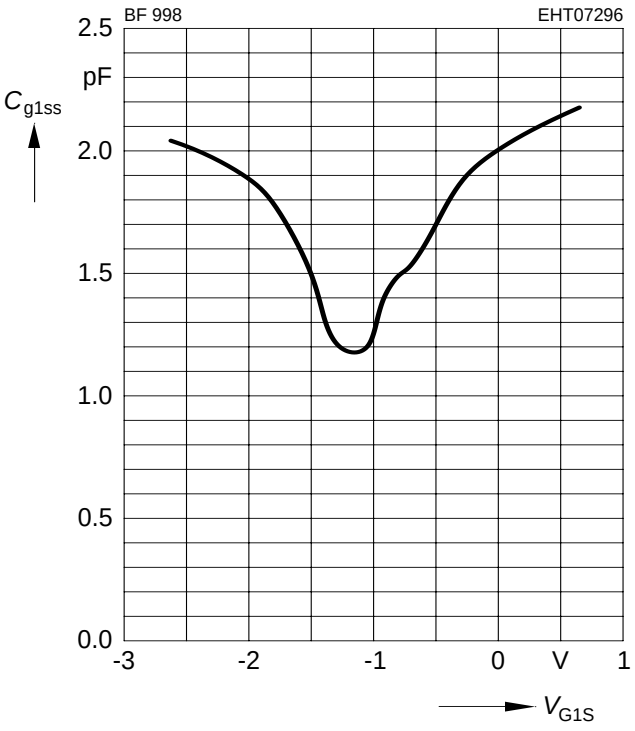
Gate 1 forward transconductance
$g_{fs1} = f(V_{G2S})$



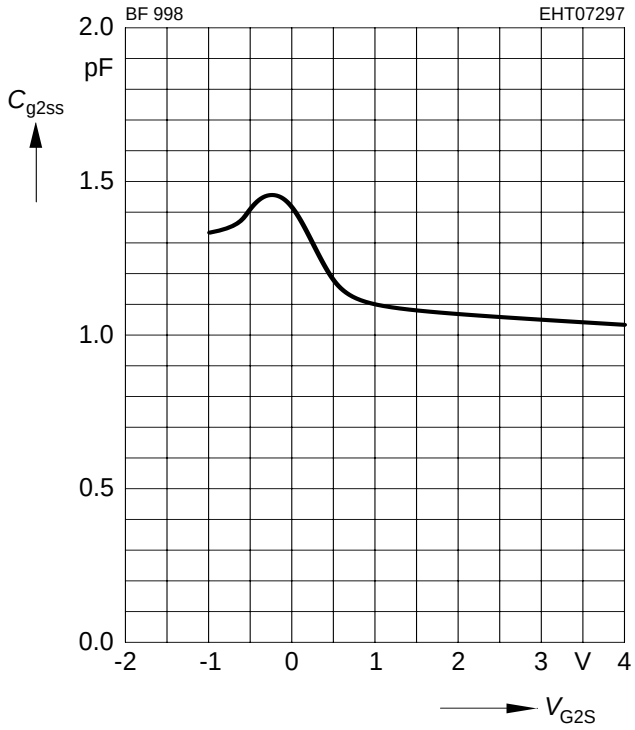
Gate 1 forward transconductance
$g_{fs1} = f(I_D)$



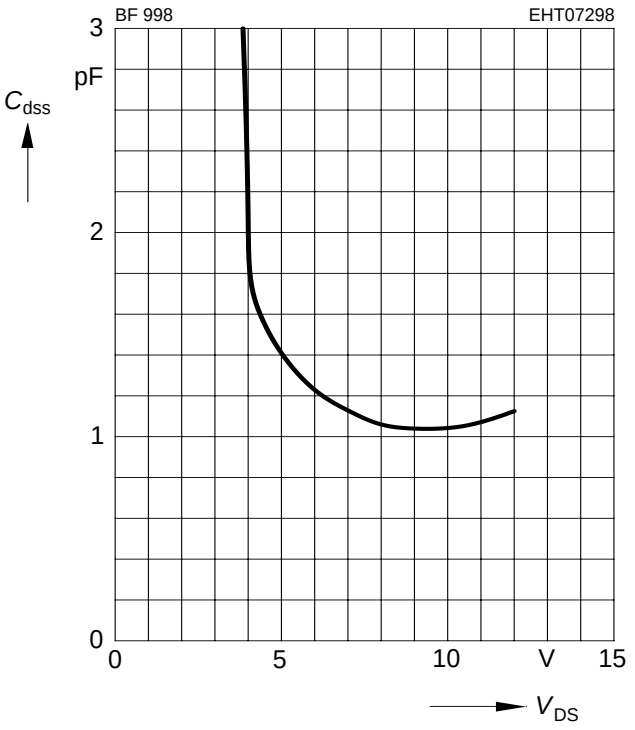
Gate 1 input capacitance $C_{g1ss} = f(V_{G1S})$



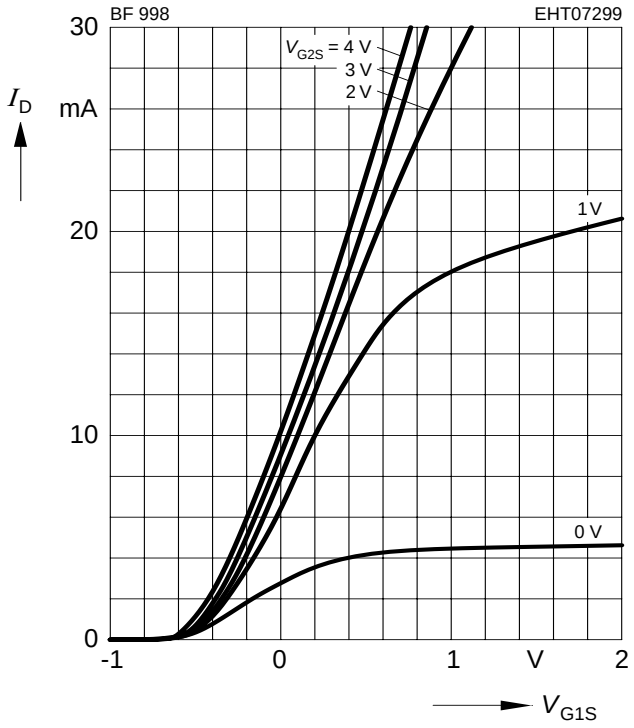
Gate 2 input capacitance $C_{g2ss} = f(V_{G2S})$



Output capacitance $C_{dss} = f(V_{DS})$

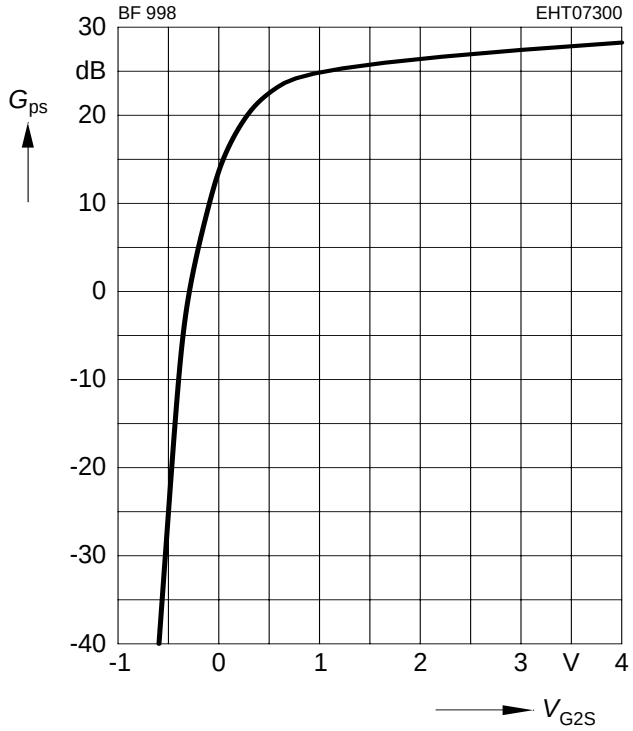


Drain current $I_D = f(V_{G1S})$



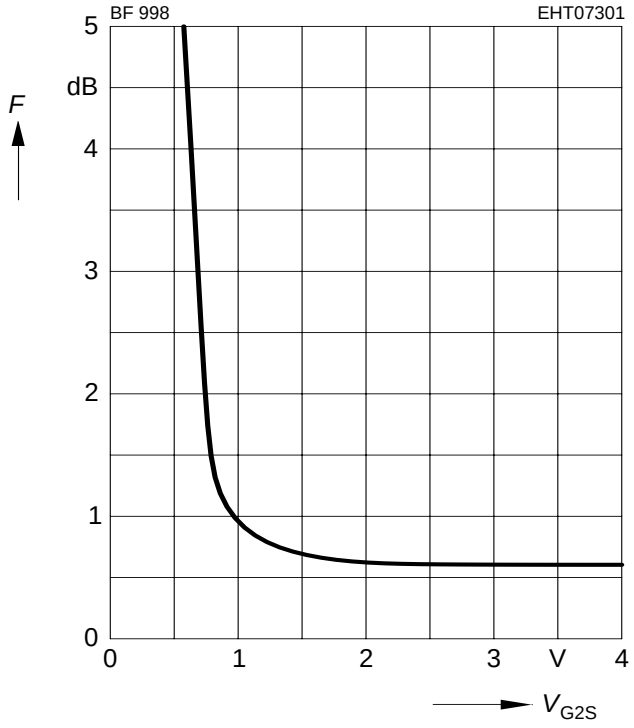
Power gain Gps $= f(V_{G2S})$

f = 200 MHz



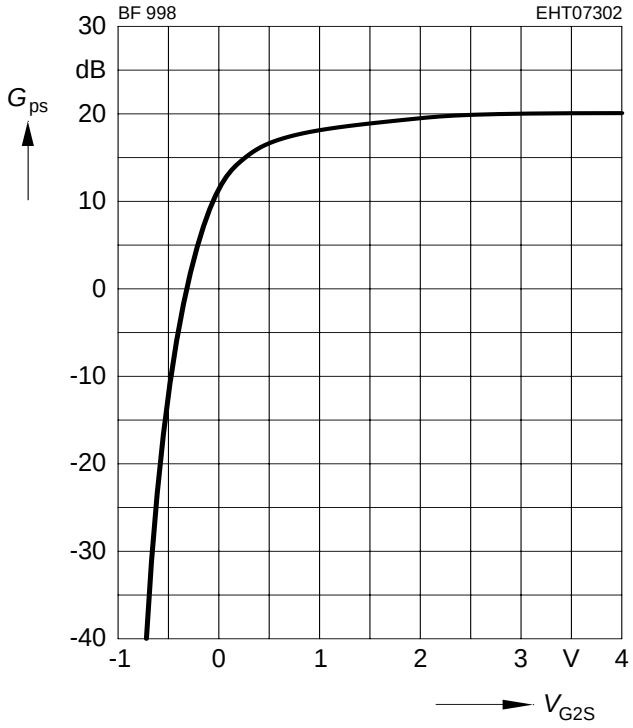
Noise figure $F = f(V_{G2S})$

f = 200 MHz



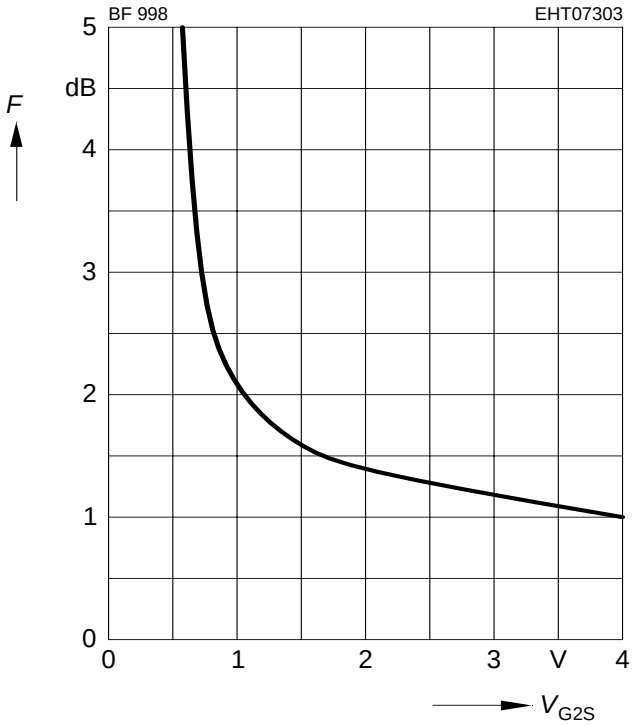
Power gain $G_{ps} = f(V_{G2S})$

f = 800 MHZ



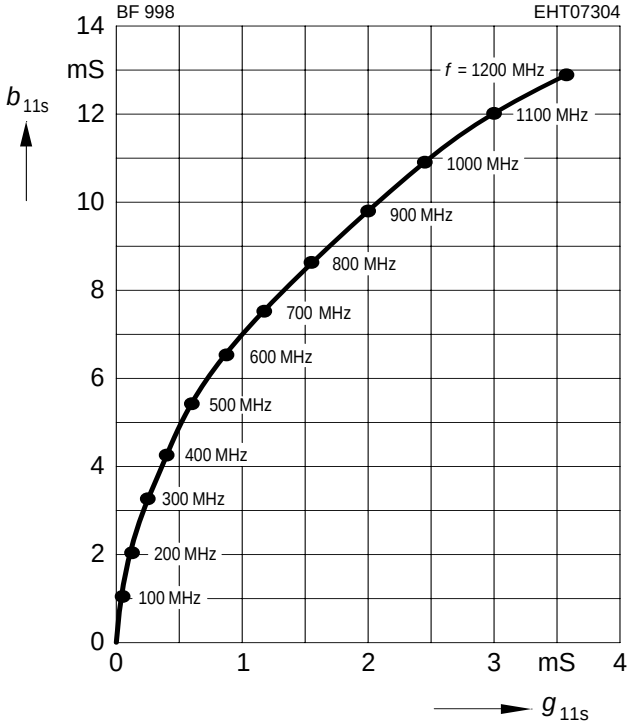
Noise figure $F = f(V_{G2S})$

f = 800 MHz



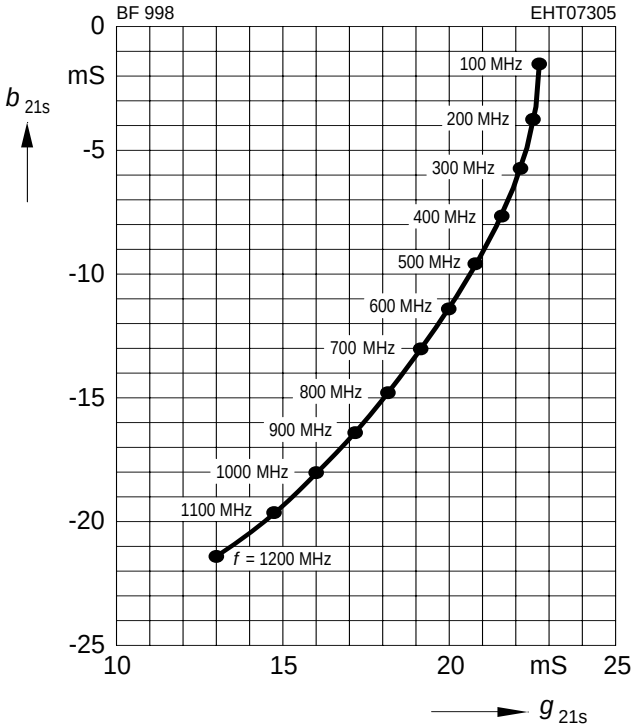
Gate 1 input admittance y_{11s}

(common source)



Gate 1 forward transfer admittance y_{21s}

(common source)



Output admittance y_{22s}

(common-source)